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November 2013

# FCB36N60N N-Channel SupreMOS<sup>®</sup> MOSFET 600 V, 36 A, 90 m $\Omega$

#### **Features**

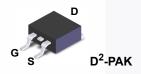
- $R_{DS(on)} = 81 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V, } I_D = 18 \text{ A}$
- Ultra Low Gate Charge (Typ. Qg = 86 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 361 pF)
- 100% Avalanche Tested
- · RoHS Compliant

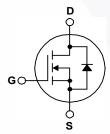
## **Applications**

- · Solar Inverter
- · AC-DC Power Supply

## Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.





## MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FCB36N60N	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		600	V	
V <sub>GSS</sub>	Gate to Source Voltage		±30	V	
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)	36	_	
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)	22.7	A	
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	108	Α	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	1800	mJ	
I <sub>AR</sub>	Avalanche Current (Note 1)		12	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		3.12	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
uv/ul	Peak Diode Recovery dv/dt	(Note 3)	20	V/ns	
В	Dower Dissinction	$(T_C = 25^{\circ}C)$	312	W	
$P_{D}$	Power Dissipation	- Derate Above 25°C	2.6	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperate	-55 to +150	°C		
T <sub>L</sub>	Maximum Lead Temperature for S	Soldering, 1/8" from Case for 5 Seconds	300	°C	

## **Thermal Characteristics**

Symbol	Parameter	FCB36N60N	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.4	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (1 in <sup>2</sup> Pad of 2-oz Copper), Max.	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max. 62.5		

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCB36N60N	FCB36N60N	D <sup>2</sup> -PAK	Tape and Reel	330 mm	24 mm	800 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}, T_C = 25^{\circ}\text{C}$	600	-	-	V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.7	-	V/°C
1	Zoro Coto Voltago Droin Current	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V	-	-	10	
I <sub>DSS</sub> Ze	Zero Gate Voltage Drain Current	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	100	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	-	-	±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	2.0	-	4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 18 A	-	81	90	$m\Omega$
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 18 A	ı	41	1	S

## **Dynamic Characteristics**

Input Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz		3595	4785	pF
Output Capacitance			149	200	pF
Reverse Transfer Capacitance			4	6	pF
Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	80	-	pF
Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 380 \text{ V}, V_{GS} = 0 \text{ V}$	-	361	-	pF
Total Gate Charge at 10V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 18 A,	-	86	112	nC
Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	15.4	-	nC
Gate to Drain "Miller" Charge	(Note 4)	-	26.4	-	nC
Equivalent Series Resistance (G-S)	f = 1 MHz	-	1	-	Ω
	Output Capacitance Reverse Transfer Capacitance Output Capacitance Effective Output Capacitance Total Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge	$\begin{array}{lll} & \text{Output Capacitance} & \text{V}_{DS} = 100 \text{ V}, \text{V}_{GS} = 0 \text{ V}, \\ f = 1 \text{ MHz} & \\ & \text{Output Capacitance} & \\ & \text{Output Capacitance} & \\ & \text{Effective Output Capacitance} & \\ & \text{Total Gate Charge at 10V} & \\ & \text{Gate to Source Gate Charge} & \\ & \text{Gate to Drain "Miller" Charge} & \\ & \text{(Note 4)} & \\ & \end{array}$	$\begin{array}{c} \text{Output Capacitance} & \text{V}_{DS} = 100 \text{ V}, \text{V}_{GS} = 0 \text{ V}, \\ \text{f} = 1 \text{ MHz} & - \\ \\ \text{Output Capacitance} & \text{V}_{DS} = 380 \text{ V}, \text{V}_{GS} = 0 \text{ V}, \text{f} = 1 \text{ MHz} \\ - \\ \text{Effective Output Capacitance} & \text{V}_{DS} = 380 \text{ V}, \text{V}_{GS} = 0 \text{ V} \\ \\ \text{Total Gate Charge at 10V} & \text{V}_{DS} = 380 \text{ V}, \text{I}_{D} = 18 \text{ A}, \\ \\ \text{Gate to Source Gate Charge} & \text{V}_{GS} = 10 \text{ V} \\ \\ \text{Gate to Drain "Miller" Charge} & \text{(Note 4)} \\ \end{array}$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	23	56	ns
t <sub>r</sub>		$V_{DD} = 380 \text{ V}, I_D = 18 \text{ A},$	- /	22	54	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{G}$ = 4.7 $\Omega$	-	94	198	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		4	18	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	36	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	108	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A,	-	574	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	10	-	μС

#### Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I<sub>AS</sub> = 12 A, R<sub>G</sub> = 25  $\Omega$ , starting T<sub>J</sub> = 25°C.
- 3. I  $_{SD}$   $\leq$  36 A, di/dt  $\leq$  200 A/ $\mu$ s, V  $_{DD}$  = 380 V, starting T  $_{J}$  = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

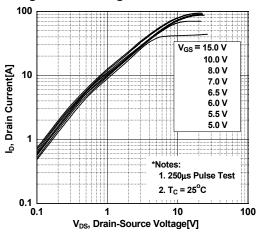


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

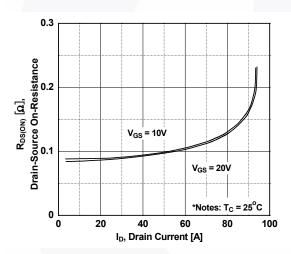


Figure 5. Capacitance Characteristics

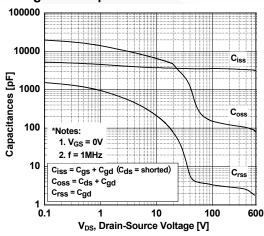


Figure 2. Transfer Characteristics

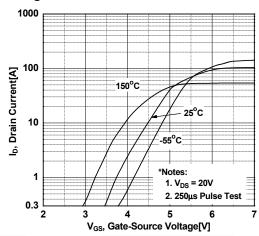


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

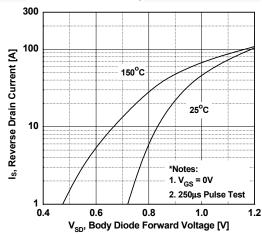
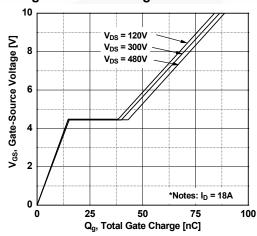
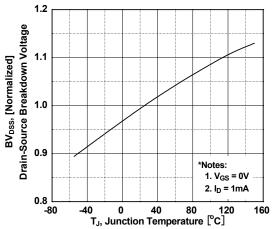


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature



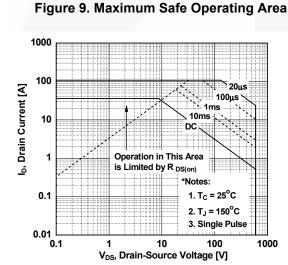


Figure 8. On-Resistance Variation vs. Temperature

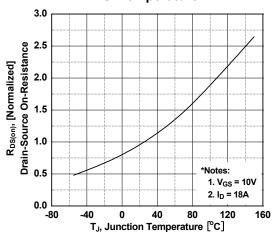


Figure 10. Maximum Drain Current vs. Case Temperature

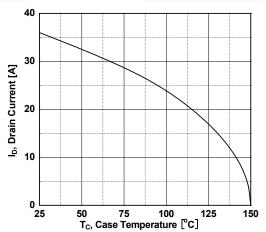
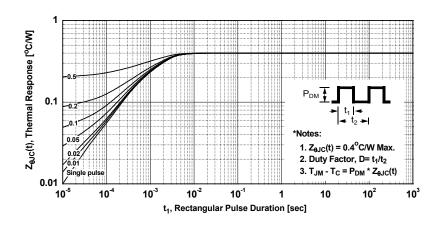


Figure 11. Transient Thermal Response Curve



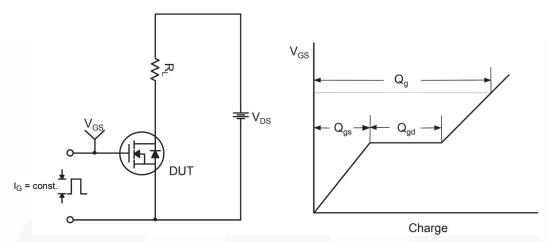


Figure 12. Gate Charge Test Circuit & Waveform

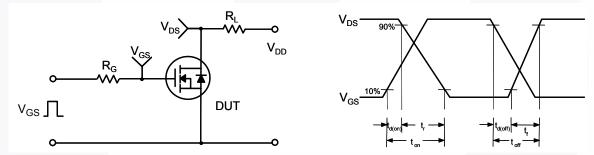


Figure 13. Resistive Switching Test Circuit & Waveforms

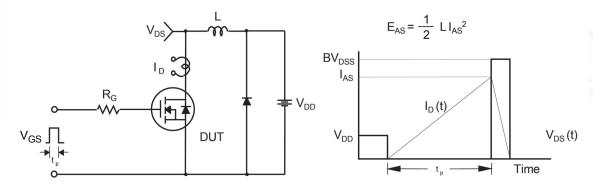


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

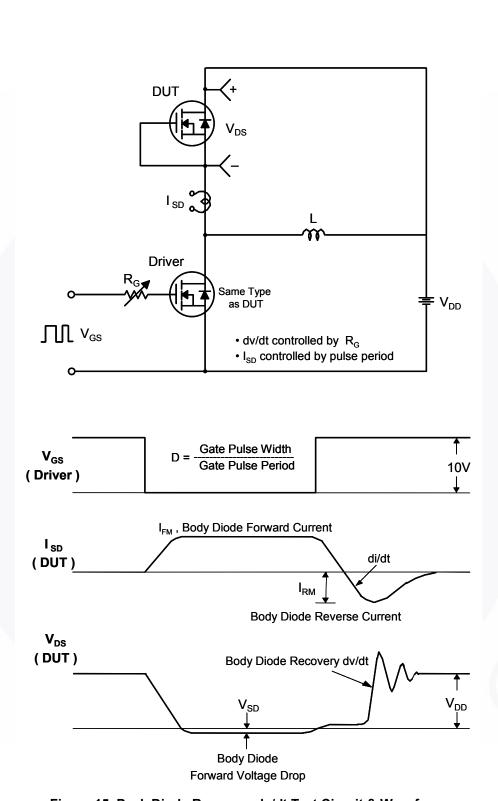


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

## **Mechanical Dimensions**

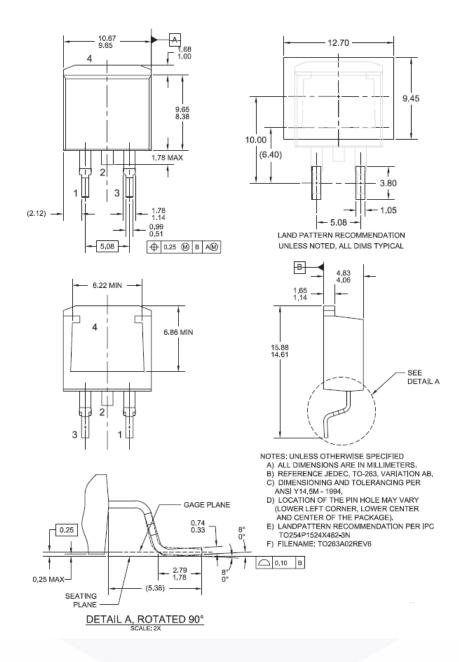


Figure 16. TO263 (D<sup>2</sup>PAK), Molded, 2-Lead, Surface Mount

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